

ABSTRACT OF THE DISCLOSURE

A frame for semiconductor packages has die-pads supported with suspending leads of individual lead frames. Semiconductor devices are mounted on the respective die-pads. These semiconductor devices are collectively molded with molding compound, and then the collectively molded semiconductor packages are cut into individual packages by means of a dicing saw. In the frame, thin parts are formed in areas corresponding to the roots of individual terminals, the thin parts being formed by half-etching metal of the areas from the front or back thereof. Alternatively, hollows are formed in areas corresponding to the roots of individual terminals.